
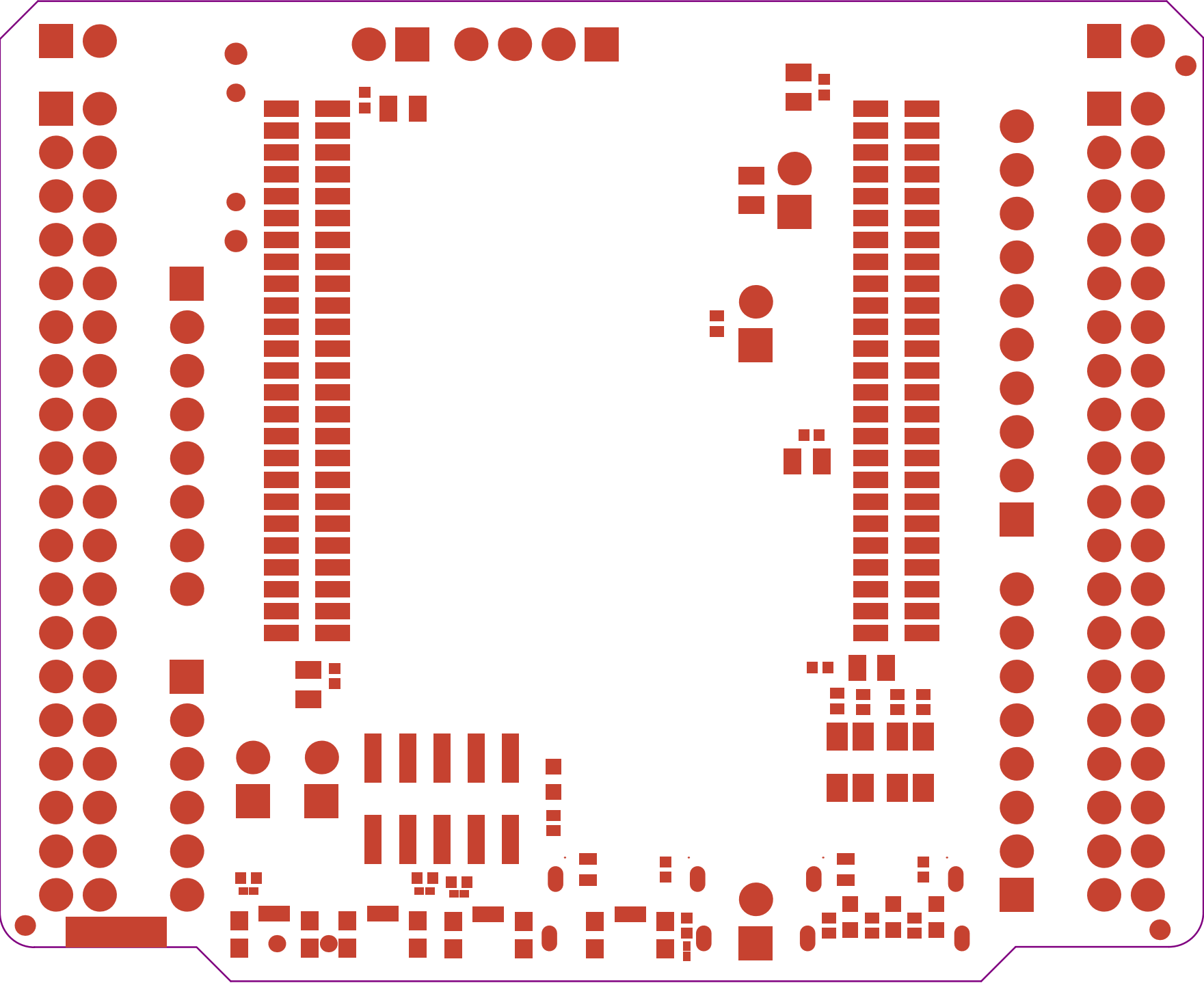

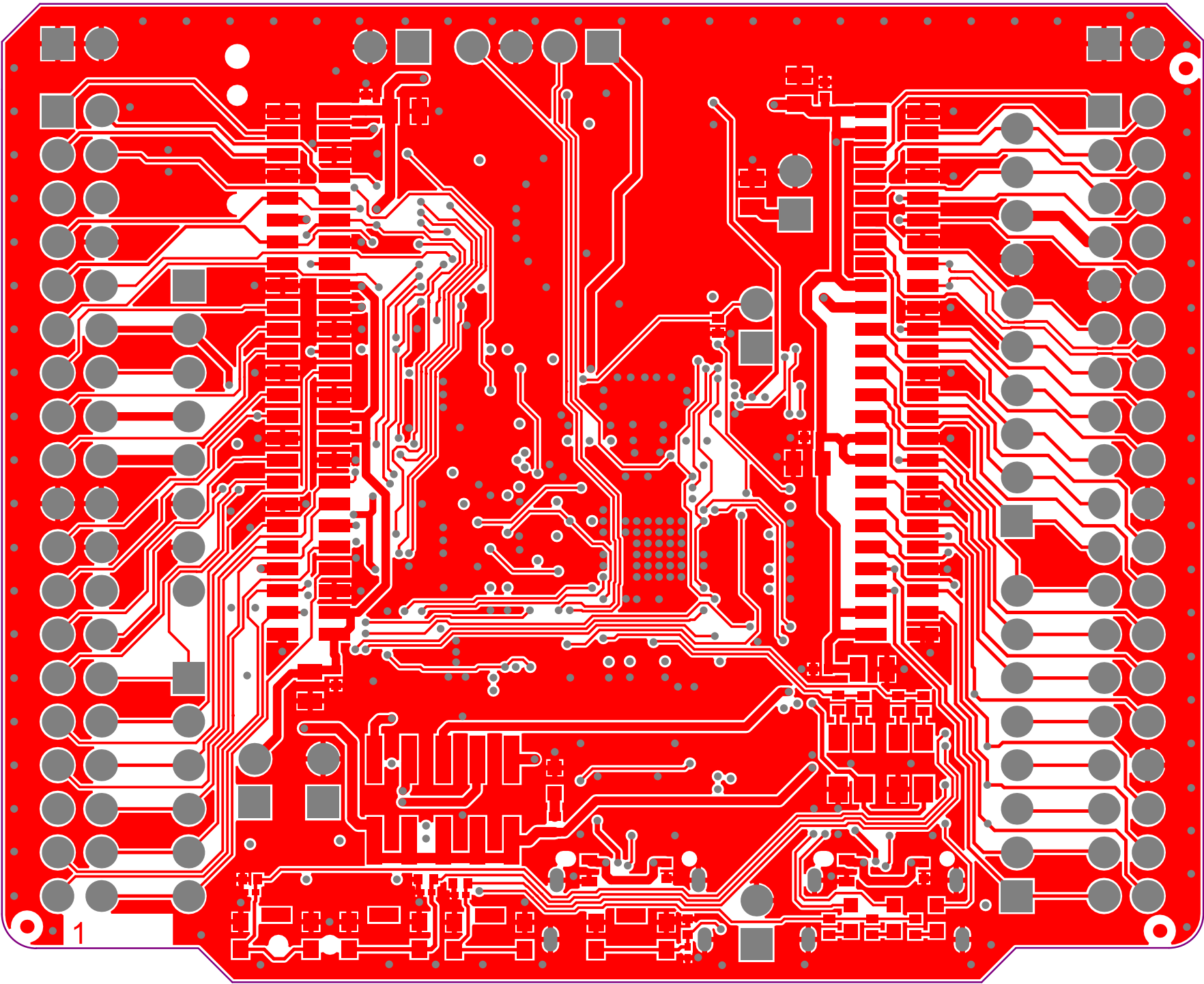



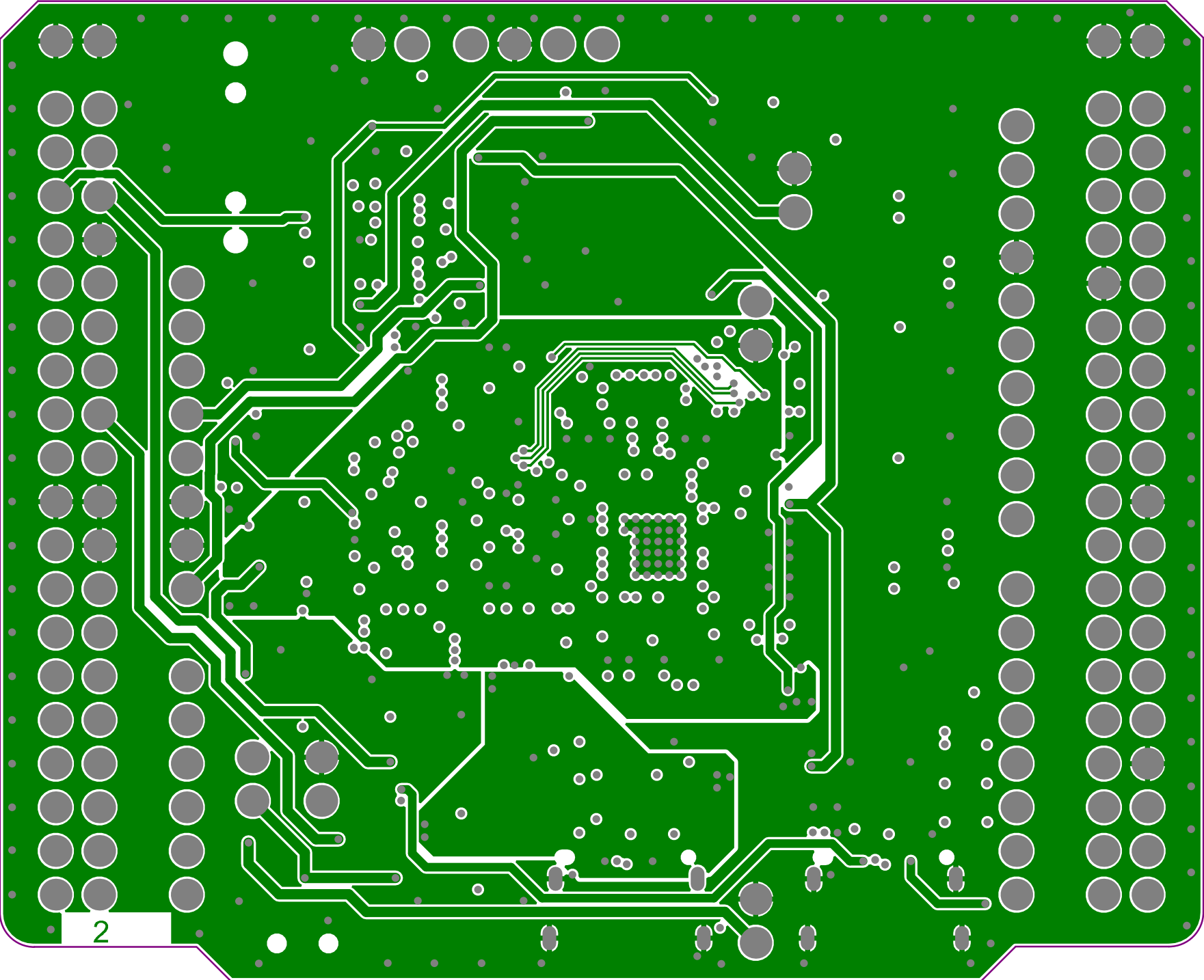
Project: NUCLEO-64 - Mezzanine Board		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1801	
Date: 08-JUN-2023	Rev: D	




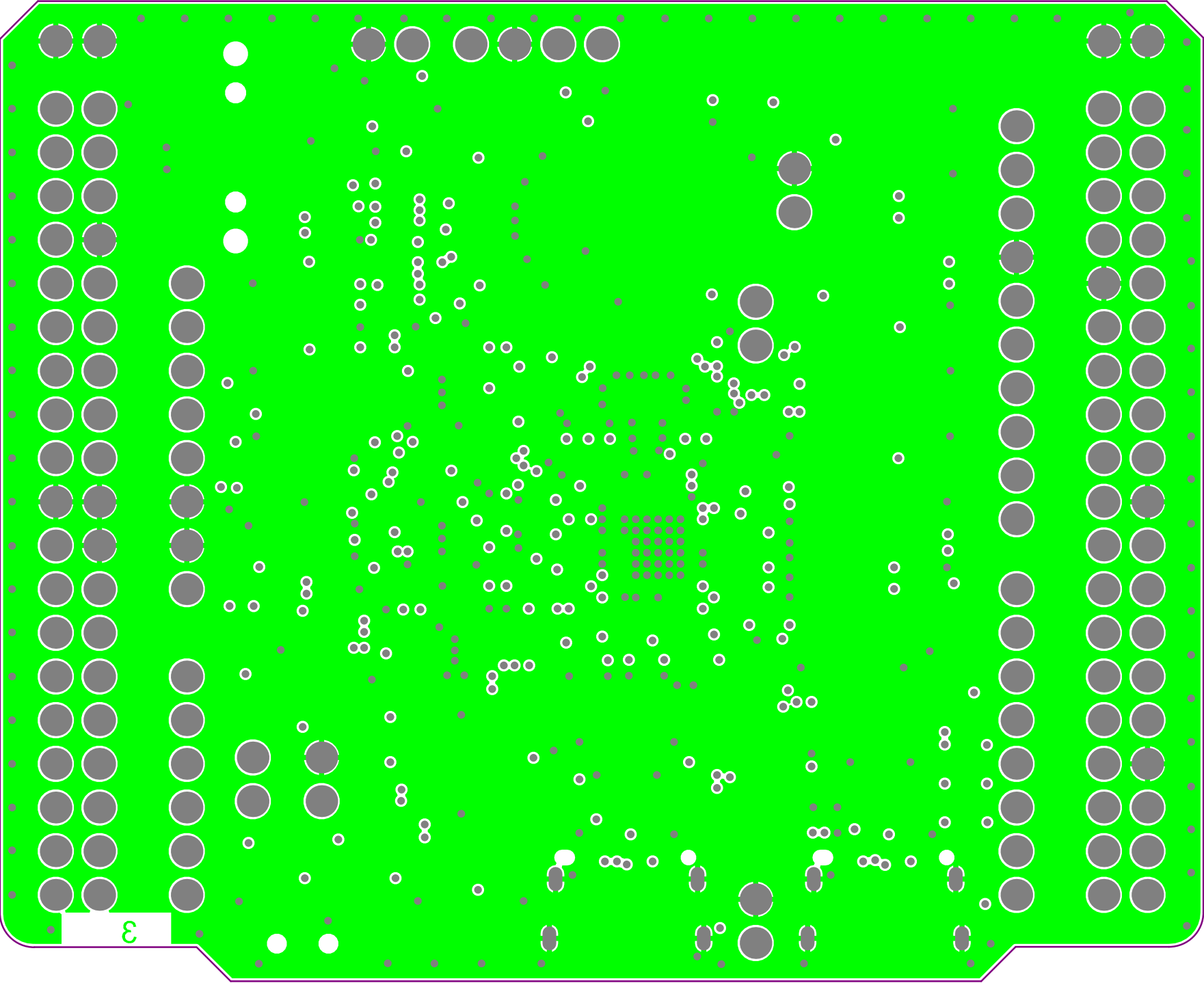
Project: NUCLEO-64 - Mezzanine Board		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1801	
Date: 08-JUN-2023	Rev: D	

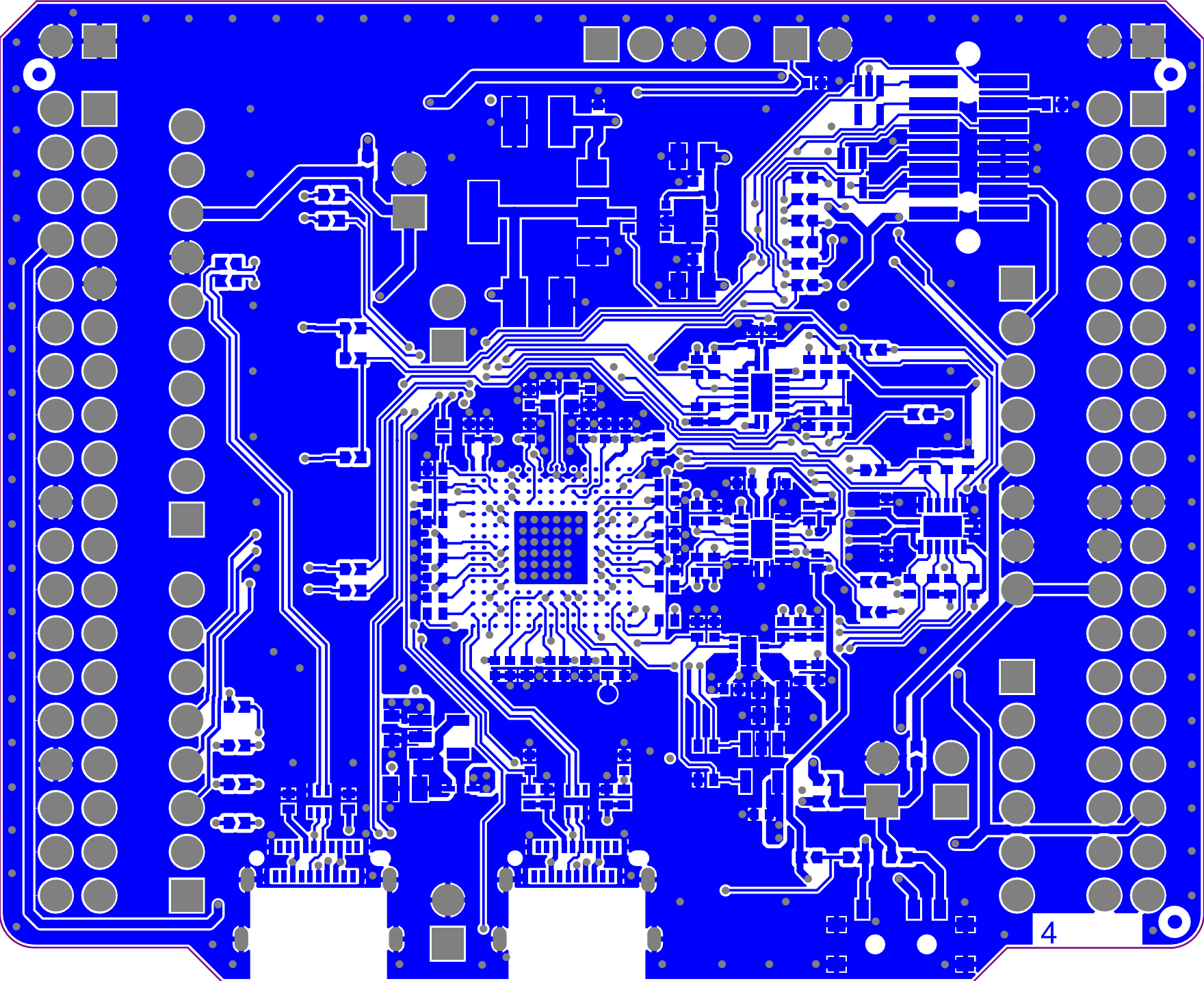


Project: NUCLEO-64 - Mezzanine Board		
Layer:	Gerber:	
Variant: [No Variations]	Ref: MB1801	
Date: 08-JUN-2023	Rev: D	



Project: NUCLEO-64 - Mezzanine Board		
Layer:	Gerber:	
Variant: [No Variations]	Ref: MB1801	
Date: 08-JUN-2023	Rev: D	





Project: NUCLEO-64 - Mezzanine Board

Layer: Bottom Layer

Variant: [No Variations]

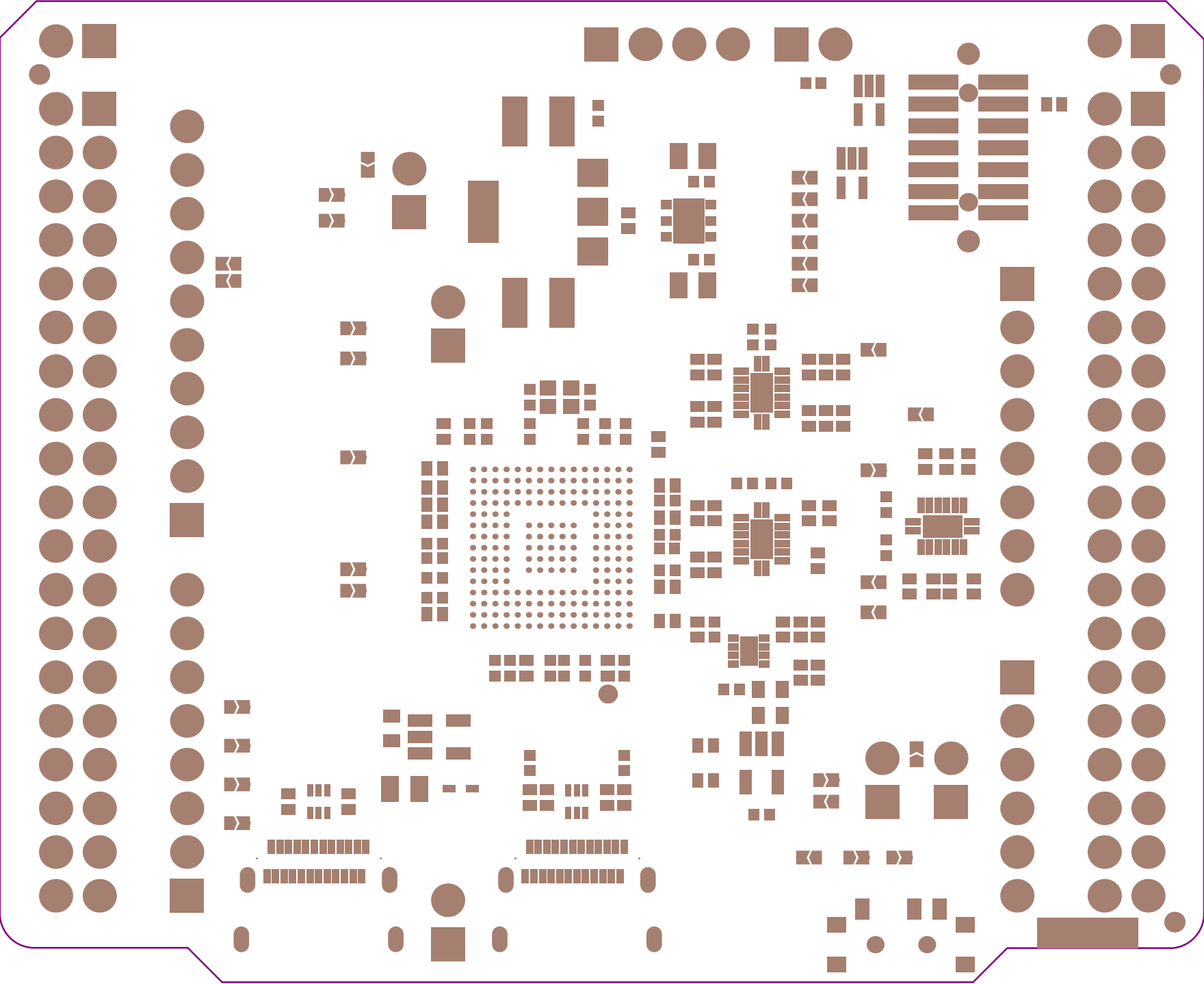
Date: 08-JUN-2023


Gerber:.GBL

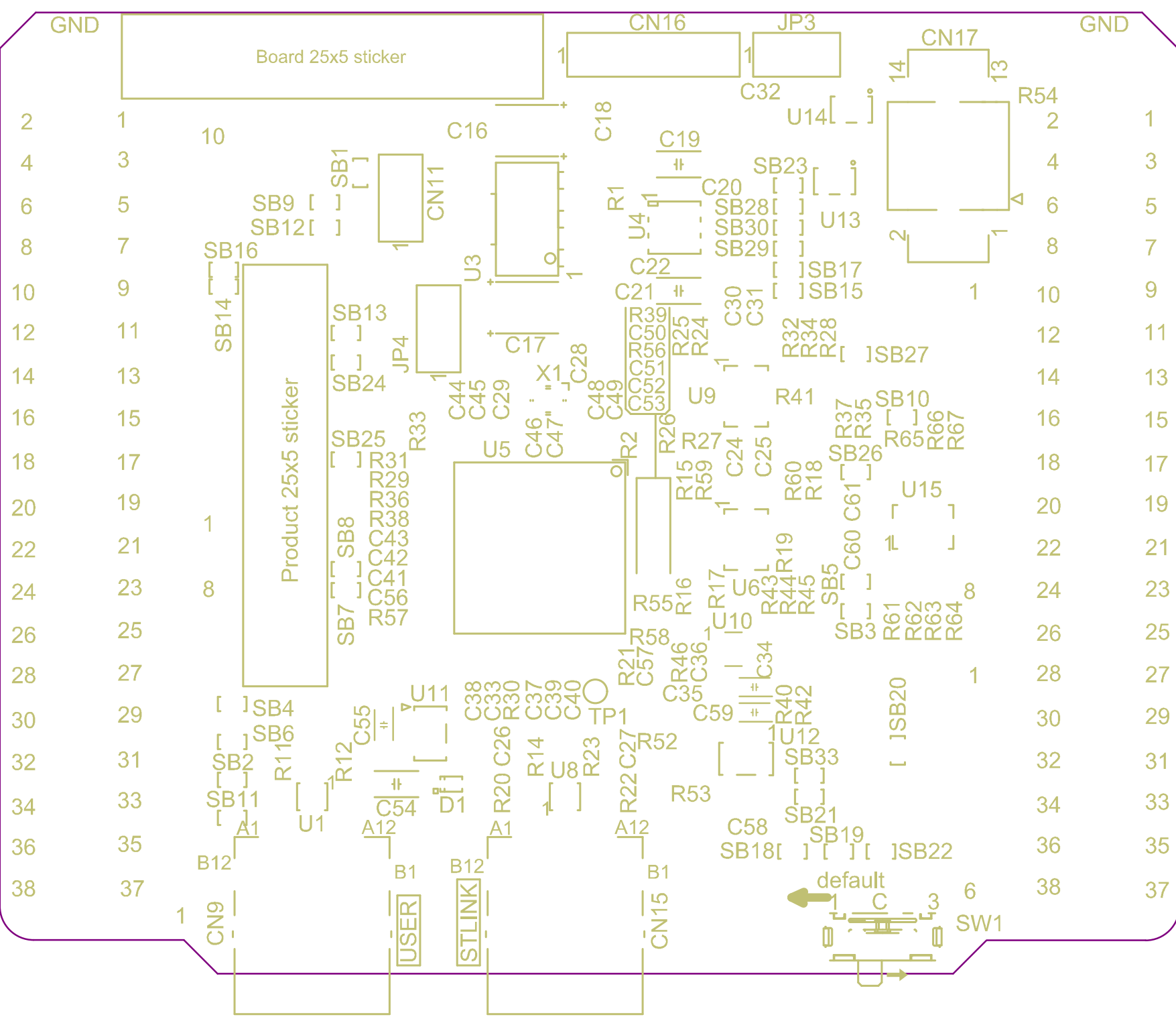
Ref: MB1801


Rev: D





Project: NUCLEO-64 - Mezzanine Board		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB1801	
Date: 08-JUN-2023	Rev: D	



Project: NUCLEO-64 - Mezzanine Board		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB1801	
Date: 08-JUN-2023	Rev: D	

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

☒ TG-170

☐ TG-150

☐ TG-140

N/A

☐ GREEN

☒ WHITE

☐ RED

☐ BLACK

☒ BLUE

☐ YELLOW

☐ BLACK

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☒ NO

☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.










SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB : TYPE 3







ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

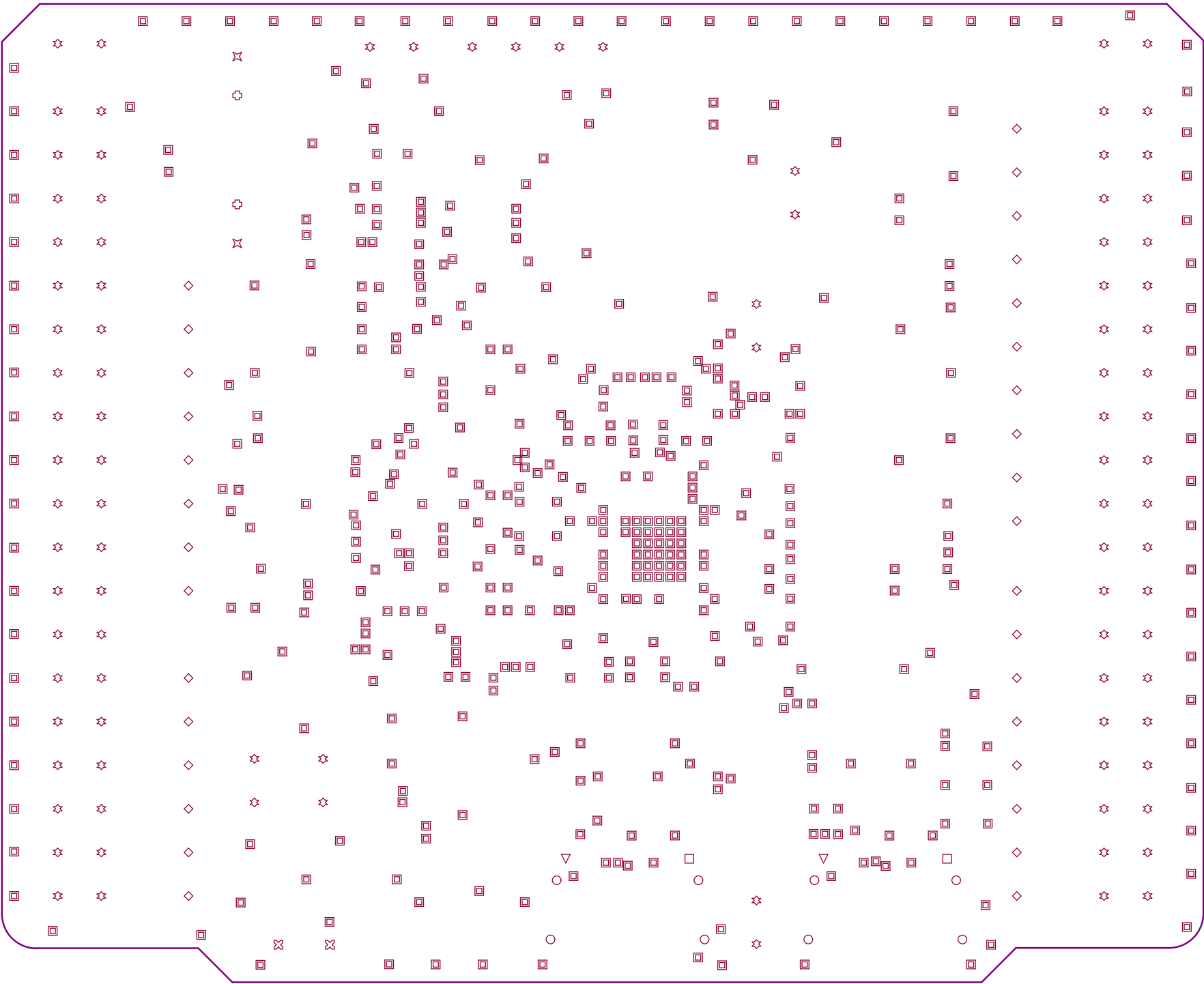
MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.150mm
GAPS : 0.120mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
	2	0,65mm (25,59mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn65m5				-	-
	2	0,65mm (25,59mil)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	c0hn65_95m5				0,95mm (37,40mil)	0,30mm (11,81mil)
	2	0,90mm (35,43mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn90m95				-	-
	2	0,97mm (38,19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn97m102				-	-
	2	1,19mm (46,85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn119m124				-	-
	8	0,50mm (19,69mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				1,10mm (43,31mil)	0,60mm (23,62mil)
	32	1,10mm (43,31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
	96	1,00mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
	473	0,20mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v45h20m0mx0				-	-
	619 Total												

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,015mm	3.5	
1	Top Layer		0,042mm		
	Dielectric 1	PP-IT-180A	0,106mm	4.2	
2	Signal Layer 1		0,035mm		
	Dielectric 2	FR-4	1,248mm	4.2	
3	Signal Layer 2		0,035mm		
	Dielectric 3	PP-IT-180A	0,106mm	4.2	
4	Bottom Layer		0,042mm		
	Bottom Solder	Solder Resist	0,015mm	3.5	
	Bottom Overlay				



Project: NUCLEO-64 - Mezzanine Board

Layer: **Drill Drawing**

Variant: [No Variations]

Date: 08-JUN-2023

Gerber: **.DRL**

Ref: MB1801

Rev: D

